

Promex Quik-Pak Return to IEEE Long Island RF/Microwave Symposium with Quick-Turn Air Cavity QFNs for Microwave, Millimeter Wave and RF Applications

Quik-Pak Open-Molded/Premolded Air Cavity Plastic QFN/SOICs (OmPPs) Available in 5 Days or Faster, Open-Cavity Plastic Packages (OcPPs) in Under 24 Hours, Custom Air Cavity and Plastic Overmolded Packages in 5 Weeks or Sooner

[Promex](#) and its [Quik-Pak Division](#) return to the [IEEE Long Island RF/Microwave Symposium](#), the area's premier annual event for engineers, managers and technical professionals in the microwave, millimeter wave and RF community. The symposium will be held on Thursday, April 18, 2019 from noon to 8 pm at the Hauppauge Radisson, 110 Motor Parkway, Hauppauge LI. In addition to the opportunity to view Quik-Pak's products, preregistered attendees will enjoy free admission to the exhibit floor, technical lectures and networking events, plus complimentary lunch and dinner.

Quik-Pak East Coast Sales Manager Bill Lawrence will be on hand with samples of Quik-Pak's [Open-Molded/Premolded Air Cavity Plastic QFN/SOICs \(OmPPs\)](#) available in five days or faster, [Open-Cavity Plastic Packages \(OcPPs\)](#) available in under 24 hours and [Custom Air Cavity and Plastic overmolded packages](#) available in five weeks or sooner after validation of the customer's design.

Quik-Pak enables its customers to ramp up from prototype design validation to full production at its ISO 13485:2016, ISO 9001:2015 and ITAR registered San Diego, CA facility. Assembly services include high-volume precision die attach, wire bond capabilities, encapsulation, flip chip and custom assembly. Quik-Pak's precision wafer processing services designed to minimize yield loss include wafer dicing, pick and place and backgrinding.

Promex / Quik-Pak
Microelectronic Packaging & Assembly Technologies

Faster Turn Time for IC Designs

- Open-Cavity Plastic Packages (OcPPs) in <24 hours
- Open-Molded/Premolded Air Cavity Plastic QFN/SOIC (OmPPs) in <5 days
- Custom Air Cavity & Plastic Overmolded Packages in 5 weeks
- Prototype to High-Volume Assembly & Wafer Prep

Advanced Packaging

- Medical, commercial, military
- SMT assembly with IC packaging
- >= 01005 component placement
- Class 100 & 1000 cleanrooms
- Hermetic, plastic, COB
- IPC-A-610 Class 3

Engineering Advantage

- Proof of concept to production
- Custom engineered flows
- Materials science expertise

Promex
408-436-0222
www.promex-ird.com

Quik-Pak
858-674-4676
www.icproto.com

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